

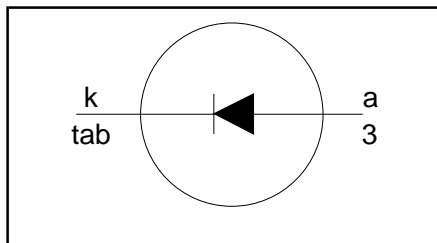
**Rectifier diodes
Schottky barrier**

PBYR1645B series

FEATURES

- Low forward volt drop
- Fast switching
- Reverse surge capability
- High thermal cycling performance
- Low thermal resistance

SYMBOL



QUICK REFERENCE DATA

$V_R = 40\text{ V} / 45\text{ V}$
$I_{F(AV)} = 16\text{ A}$
$V_F \leq 0.57\text{ V}$

GENERAL DESCRIPTION

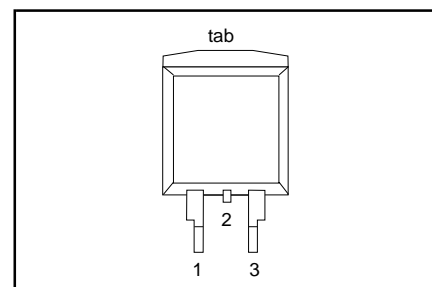
Schottky rectifier diodes in a plastic envelope. Intended for use as output rectifiers in low voltage, high frequency switched mode power supplies.

The PBYR1645B series is supplied in the surface mounting SOT404 package.

PINNING

PIN	DESCRIPTION
1	no connection
2	cathode ¹
3	anode
tab	cathode

SOT404



LIMITING VALUES

Limiting values in accordance with the Absolute Maximum System (IEC 134)

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.		UNIT
				40B	45B	
V_{RRM}	Peak repetitive reverse voltage	PBYR16 $T_{mb} \leq 116\text{ °C}$	-	40	45	V
V_{RWM}	Working peak reverse voltage		-	40	45	V
V_R	Continuous reverse voltage		-	40	45	V
$I_{F(AV)}$	Average rectified forward current	square wave; $\delta = 0.5$; $T_{mb} \leq 131\text{ °C}$	-	16		A
I_{FRM}	Repetitive peak forward current	square wave; $\delta = 0.5$; $T_{mb} \leq 131\text{ °C}$	-	32		A
I_{FSM}	Non-repetitive peak forward current	$t = 10\text{ ms}$	-	135		A
		$t = 8.3\text{ ms}$	-	150		A
I_{RRM}	Peak repetitive reverse surge current	sinusoidal; $T_j = 125\text{ °C}$ prior to surge; with reapplied $V_{RRM(max)}$ pulse width and repetition rate limited by T_{jmax}	-	1		A
T_j	Operating junction temperature		-	150		°C
T_{stg}	Storage temperature		- 65	175		°C

¹ it is not possible to make connection to pin 2 of the SOT404 package.

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THERMAL RESISTANCES

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$R_{th\ j-mb}$	Thermal resistance junction to mounting base		-	-	1.5	K/W
$R_{th\ j-a}$	Thermal resistance junction to ambient	pcb mounted, minimum footprint, FR4 board	-	50	-	K/W

ELECTRICAL CHARACTERISTICS

$T_j = 25\text{ }^\circ\text{C}$ unless otherwise specified

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V_F	Forward voltage	$I_F = 16\text{ A}$; $T_j = 125\text{ }^\circ\text{C}$	-	0.53	0.57	V
		$I_F = 16\text{ A}$	-	0.55	0.63	V
I_R	Reverse current	$V_R = V_{RWM}$	-	0.2	1.7	mA
		$V_R = V_{RWM}$; $T_j = 100\text{ }^\circ\text{C}$	-	27	40	mA
C_d	Junction capacitance	$V_R = 5\text{ V}$; $f = 1\text{ MHz}$; $T_j = 25\text{ }^\circ\text{C}$ to $125\text{ }^\circ\text{C}$	-	470	-	pF

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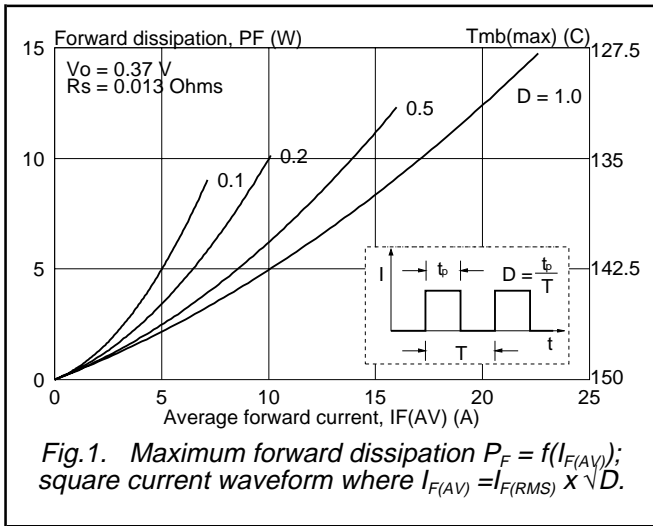


Fig.1. Maximum forward dissipation $P_F = f(I_{F(AV)})$; square current waveform where $I_{F(AV)} = I_{F(RMS)} \times \sqrt{D}$.

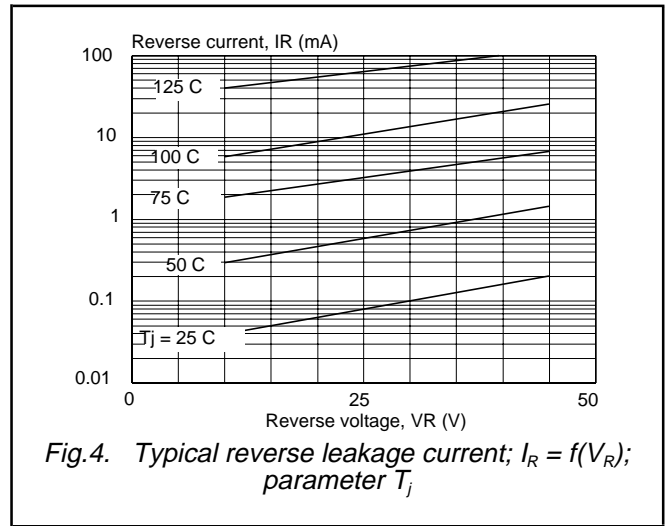


Fig.4. Typical reverse leakage current; $I_R = f(V_R)$; parameter T_j .

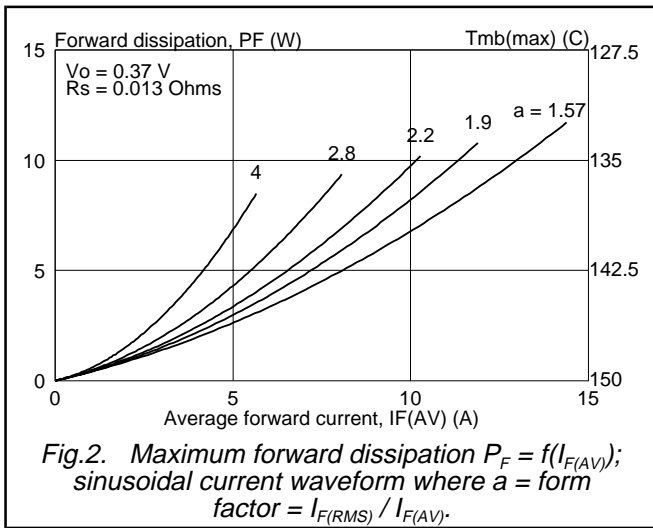


Fig.2. Maximum forward dissipation $P_F = f(I_{F(AV)})$; sinusoidal current waveform where $a = \text{form factor} = I_{F(RMS)} / I_{F(AV)}$.

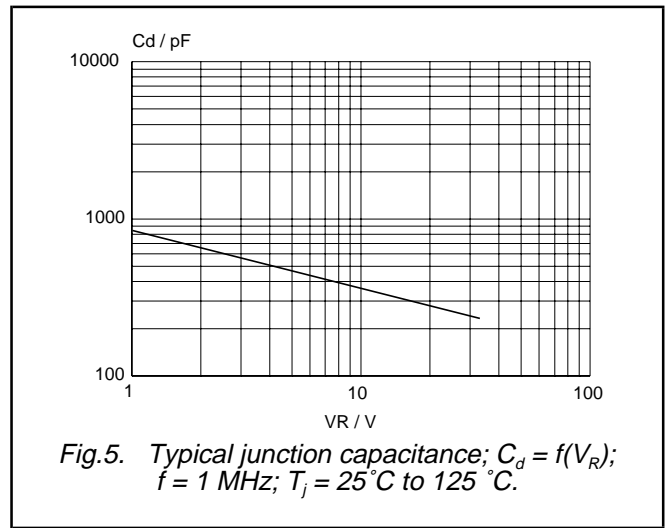


Fig.5. Typical junction capacitance; $C_d = f(V_R)$; $f = 1\text{ MHz}$; $T_j = 25\text{ C to }125\text{ C}$.

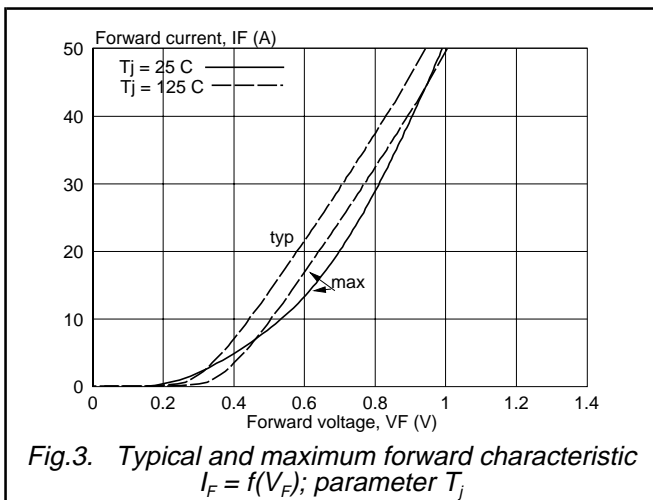


Fig.3. Typical and maximum forward characteristic $I_F = f(V_F)$; parameter T_j .

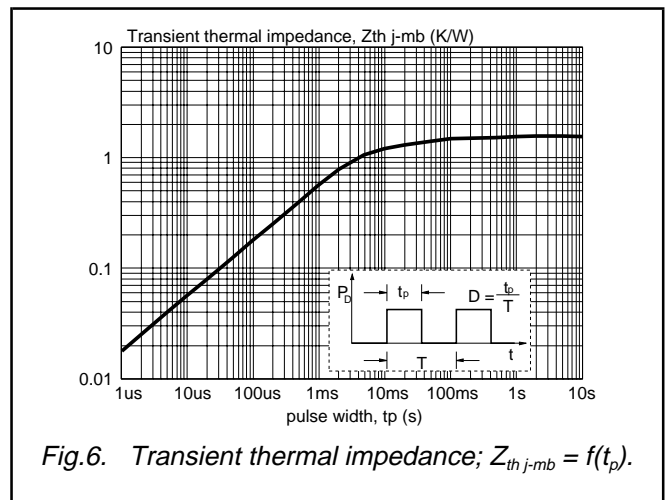
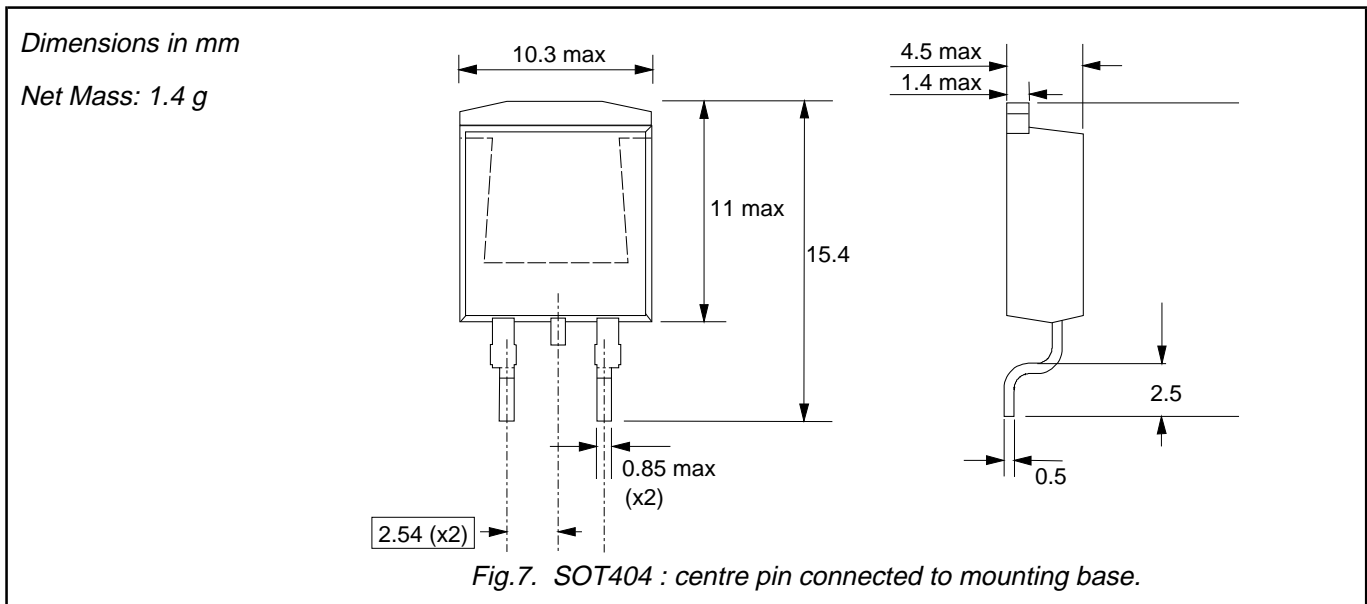


Fig.6. Transient thermal impedance; $Z_{th\ j-mb} = f(t_p)$.

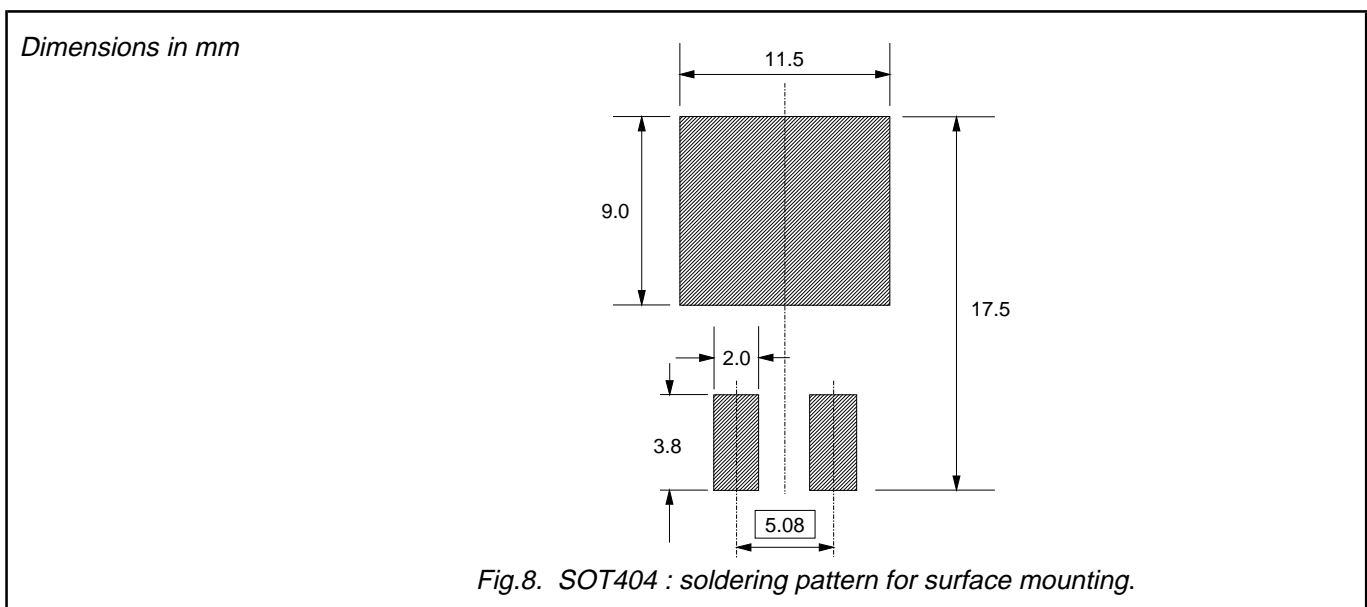
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MECHANICAL DATA



MOUNTING INSTRUCTIONS



Notes

1. Observe the general handling precautions for electrostatic-discharge sensitive devices (ESDs) to prevent damage to MOS gate oxide.
2. Epoxy meets UL94 V0 at 1/8".

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DEFINITIONS

Data sheet status	
Objective specification	This data sheet contains target or goal specifications for product development.
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.
Product specification	This data sheet contains final product specifications.
Limiting values	
Limiting values are given in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of this specification is not implied. Exposure to limiting values for extended periods may affect device reliability.	
Application information	
Where application information is given, it is advisory and does not form part of the specification.	
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